



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-04-10
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TS1852IST	EYE3*A852AR6	A	ZS1A	2013-04-10
Amount		UoM	Unit type	ST ECOPACK Grade
26.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	3.00,3.00,0.85	8	gull wing	
Comment	MSOP/TSSOP 8 BODY3.00 PITCH0.65			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 Dec 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EYE3*A852AR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	1.427	mg	supplier	Silicon Die	Silicon (Si)	7440-21-3		1.418	mg	993693	54538
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	6307	346
Lead-frame	Copper & its alloys	10.241	mg	supplier	alloy	Copper	7440-50-8		9.889	mg	966006	380346
Lead-frame				supplier	alloy	Iron	7439-89-6		0.231	mg	22565	8885
Lead-frame				supplier	alloy	Phosphorus	7723-14-0		0.002	mg	195	77
Lead-frame				supplier	alloy	Zinc	7440-66-6		0.013	mg	1270	500
Lead-frame				supplier	metallization	Silver	7440-22-4		0.102	mg	9964	3923
Soft solder	Solder	0.528	mg	supplier	solder	Silver	7440-22-4		0.424	mg	803030	16308
Soft solder				supplier	solder	Carbocyclic Acrylates	Proprietary		0.053	mg	100379	2038
Soft solder				supplier	solder	Bismaleimide resin	Proprietary		0.016	mg	30303	615
Soft solder				supplier	solder	2-preponoic acid, 2-methyl	68586-19-6		0.016	mg	30303	615
Soft solder				supplier	solder	Additive	Proprietary		0.016	mg	30303	615
Soft solder				supplier	solder	Dicumyl peroxide	80-43-3		0.003	mg	5682	115
Bonding wire	Other inorganic materials	0.457	mg	supplier	wire	Gold (Au)	7440-57-5		0.457	mg	1000000	17577
Encapsulation	Other Organic Materials	12.7	mg	supplier	mold compound	Epoxy resin-1	Proprietary		0.381	mg	30009	14654
Encapsulation				supplier	mold compound	Epoxy resin-2	Proprietary		0.381	mg	30009	14654
Encapsulation				supplier	mold compound	Phenol resin	Proprietary		0.572	mg	45054	22000
Encapsulation				supplier	mold compound	Silica	60676-86-0		11.083	mg	872952	426269
Encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.025	mg	1969	962
Encapsulation				supplier	mold compound	Others (max2%)	-		0.254	mg	20006	9769
connections coating	Solder	0.655	mg	supplier	solder alloy	Tin	7440-31-5		0.655	mg	1000000	25192